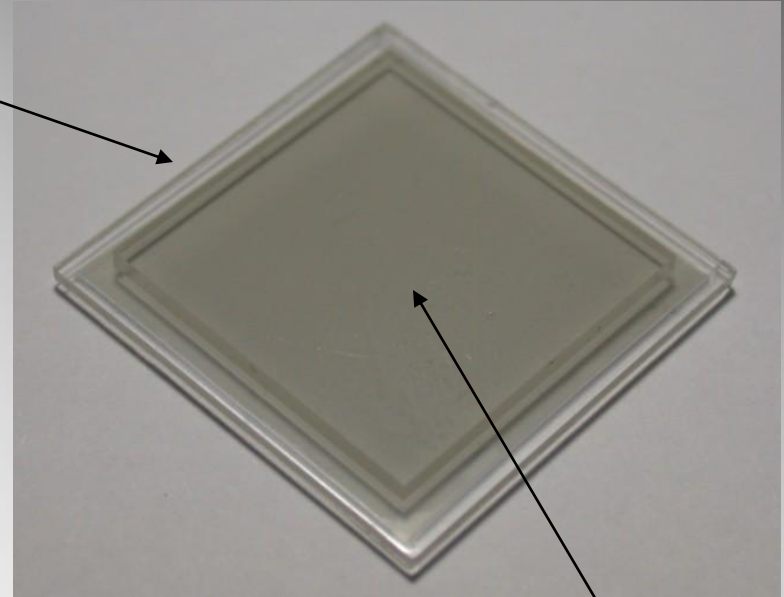


# Test Cell Conditioner (TCC)

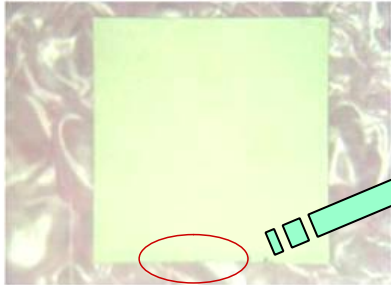
Substrate



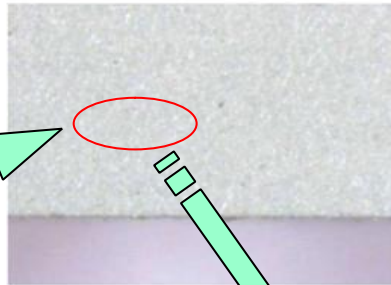
TCC Polymer

TCC Polymer Material Polishes and Collects Debris

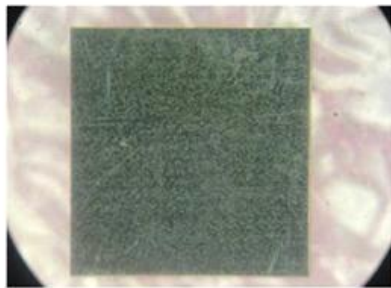
Top View



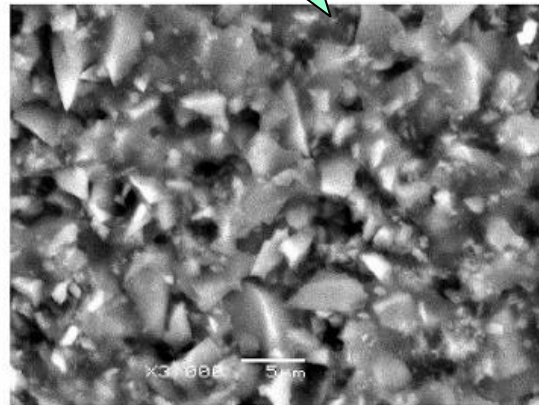
Zoom



Bottom View



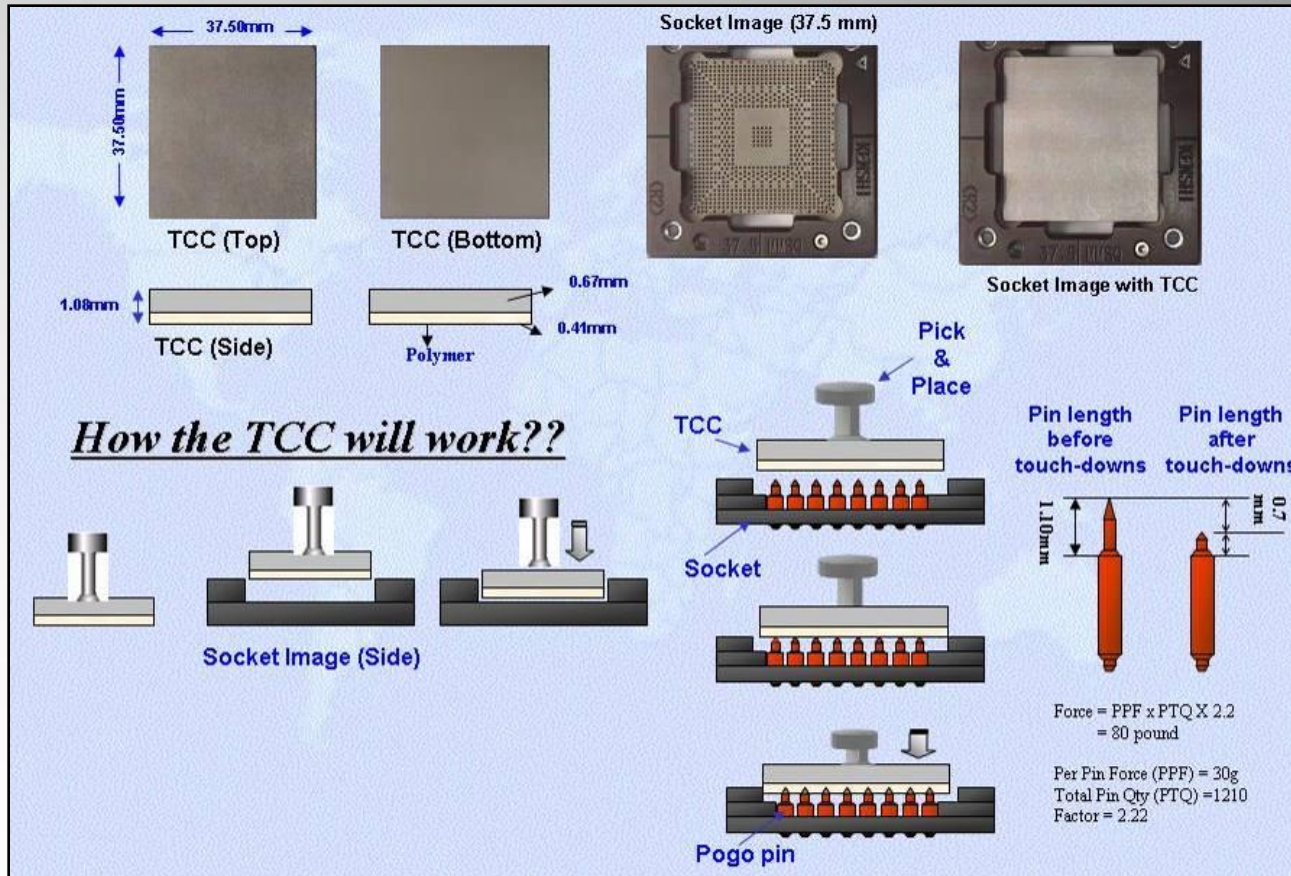
Magnified (x3000)



Abrasive particles distributed within proprietary, 100% cross linked and completely solid polymer material

Temperature range = -50 to +200C

# Debris Removal at Package Test



- Polymer material applied to the “bottom side” of the package.
- Polymer material actuated into contact with the spring pins to remove and collect debris.
- Polymer material compressed against socket floor to collect loose debris.
- US and Foreign Patents pending